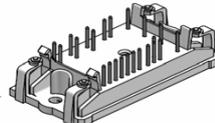
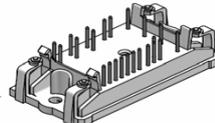
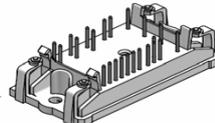
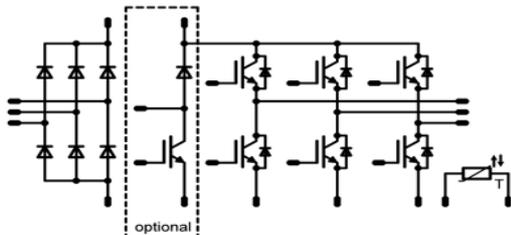
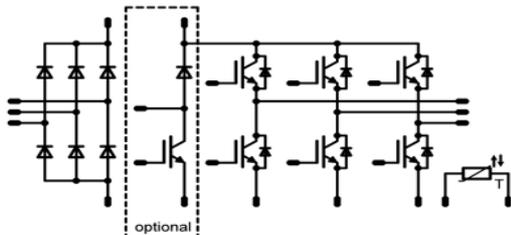
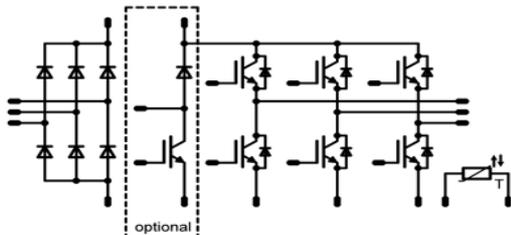


<i>flowPIM 0</i>	1200 V/8 A				
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr style="background-color: #000080; color: white;"> <th style="text-align: center; padding: 2px;">Features</th> </tr> <tr> <td style="padding: 2px;"> <ul style="list-style-type: none"> <li>Clip in PCB mountin</li> <li>Trench Fieldstop IGBT's for low saturation losses</li> <li>Optional w/o BRC</li> </ul> </td> </tr> </table>	Features	<ul style="list-style-type: none"> <li>Clip in PCB mountin</li> <li>Trench Fieldstop IGBT's for low saturation losses</li> <li>Optional w/o BRC</li> </ul>	<table border="1" style="width: 100%; border-collapse: collapse;"> <tr style="background-color: #000080; color: white;"> <th style="text-align: center; padding: 2px;">flowPIM 0</th> </tr> <tr> <td style="text-align: center; padding: 5px;">  </td> </tr> </table>	flowPIM 0	
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<ul style="list-style-type: none"> <li>V23990-P549-A01-PM</li> <li>V23990-P549-C01-PM without BRC</li> </ul>					

### Maximum Ratings

$T_J=25^{\circ}\text{C}$ , unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
<b>Input Rectifier Diode</b>				
Repetitive peak reverse voltage	$V_{RRM}$		1600	V
DC forward current	$I_{FAV}$	$T_J=T_{Jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$	34 46	A
Surge forward current	$I_{FSM}$	$t_p=10\text{ms}$ $T_J=25^{\circ}\text{C}$	370	A
I2t-value	$I^2t$		370	$\text{A}^2\text{s}$
Power dissipation per Diode	$P_{tot}$	$T_J=T_{Jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$	39 59	W
Maximum Junction Temperature	$T_{Jmax}$		150	$^{\circ}\text{C}$
<b>Inverter Transistor</b>				
Collector-emitter break down voltage	$V_{CE}$		1200	V
DC collector current	$I_C$	$T_J=T_{Jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$	13 16	A
Repetitive peak collector current	$I_{Cpulse}$	$t_p$ limited by $T_{Jmax}$	24	A
Turn off safe operating area		$V_{CE} \leq 1200\text{V}$ , $T_J \leq T_{op max}$	24	A
Power dissipation per IGBT	$P_{tot}$	$T_J=T_{Jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$	35 53	W
Gate-emitter peak voltage	$V_{GE}$		$\pm 20$	V
Short circuit ratings	$t_{SC}$ $V_{CC}$	$T_J \leq 150^{\circ}\text{C}$ $V_{GE} = 15\text{V}$	10 1200	$\mu\text{s}$ V
Maximum Junction Temperature	$T_{Jmax}$		150	$^{\circ}\text{C}$

## Maximum Ratings

 $T_j=25^{\circ}\text{C}$ , unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
-----------	--------	-----------	-------	------

### Inverter Diode

Peak Repetitive Reverse Voltage	$V_{RRM}$	$T_j=25^{\circ}\text{C}$	1200	V
DC forward current	$I_F$	$T_j=T_{jmax}$	$T_h=80^{\circ}\text{C}$	25
			$T_c=80^{\circ}\text{C}$	33
Repetitive peak forward current	$I_{FRM}$	$t_p$ limited by $T_{jmax}$	20	A
Power dissipation per Diode	$P_{tot}$	$T_j=T_{jmax}$	$T_h=80^{\circ}\text{C}$	29
			$T_c=80^{\circ}\text{C}$	42
Maximum Junction Temperature	$T_{jmax}$		150	$^{\circ}\text{C}$

### Brake Transistor

Collector-emitter break down voltage	$V_{CE}$		1200	V
DC collector current	$I_C$	$T_j=T_{jmax}$	$T_h=80^{\circ}\text{C}$	12
			$T_c=80^{\circ}\text{C}$	16
Repetitive peak collector current	$I_{Cpuls}$	$t_p$ limited by $T_{jmax}$	24	A
Turn off safe operating area		$V_{CE} \leq 1200\text{V}$ , $T_j \leq T_{jmax}$	24	A
Power dissipation per IGBT	$P_{tot}$	$T_j=T_{jmax}$	$T_h=80^{\circ}\text{C}$	33
			$T_c=80^{\circ}\text{C}$	51
Gate-emitter peak voltage	$V_{GE}$		$\pm 20$	V
Short circuit ratings	$t_{SC}$	$T_j \leq 150^{\circ}\text{C}$	10	$\mu\text{s}$
	$V_{CC}$	$V_{GE}=15\text{V}$	1200	V
Maximum Junction Temperature	$T_{jmax}$		150	$^{\circ}\text{C}$

### Brake Diode

Peak Repetitive Reverse Voltage	$V_{RRM}$	$T_j=25^{\circ}\text{C}$	1200	V
DC forward current	$I_F$	$T_j=T_{jmax}$	$T_h=80^{\circ}\text{C}$	7
			$T_c=80^{\circ}\text{C}$	7
Repetitive peak forward current	$I_{FRM}$	$t_p$ limited by $T_{jmax}$	8	A
Power dissipation per Diode	$P_{tot}$	$T_j=T_{jmax}$	$T_h=80^{\circ}\text{C}$	18
			$T_c=80^{\circ}\text{C}$	27
Maximum Junction Temperature	$T_{jmax}$		150	$^{\circ}\text{C}$

### Thermal Properties

Storage temperature	$T_{slg}$		-40...+125	$^{\circ}\text{C}$
Operation temperature under switching condition	$T_{op}$		-40...+( $T_{jmax} - 25$ )	$^{\circ}\text{C}$

### Insulation Properties

Insulation voltage	$V_{is}$	$t=2\text{s}$ DC voltage	4000	V
Creepage distance			min 12,7	mm
Clearance			min 12,7	mm
Comparative tracking index	CTI		>200	

**Characteristic Values**

Parameter	Symbol	Conditions					Value			Unit
		$V_{GE}[V]$ or $V_{GS}[V]$	$V_r[V]$ or $V_{CE}[V]$ or $V_{DS}[V]$	$I_c[A]$ or $I_F[A]$ or $I_D[A]$	$T_j$	Min	Typ	Max		
<b>Input Rectifier Diode</b>										
Forward voltage	$V_F$				35	$T_j=25^\circ C$ $T_j=125^\circ C$	1	1,19 1,17	1,7	V
Threshold voltage (for power loss calc. only)	$V_{to}$				35	$T_j=25^\circ C$ $T_j=125^\circ C$		0,91 0,79		V
Slope resistance (for power loss calc. only)	$r_t$				35	$T_j=25^\circ C$ $T_j=125^\circ C$		8 11		m $\Omega$
Reverse current	$I_r$			1600		$T_j=25^\circ C$ $T_j=125^\circ C$			0,1	mA
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal grease thickness $\leq$ 50um $\lambda = 1$ W/mK						1,80		K/W
<b>Inverter Transistor</b>										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}$			0,0003	$T_j=25^\circ C$ $T_j=125^\circ C$	5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		8	$T_j=25^\circ C$ $T_j=125^\circ C$	1,35	1,64 1,83	2,05	V
Collector-emitter cut-off current incl. Diode	$I_{CES}$		0	1200		$T_j=25^\circ C$ $T_j=125^\circ C$			0,05	mA
Gate-emitter leakage current	$I_{GES}$		20	0		$T_j=25^\circ C$ $T_j=125^\circ C$			120	nA
Integrated Gate resistor	$R_{gint}$							none		$\Omega$
Turn-on delay time	$t_{d(on)}$	$R_{goff}=64 \Omega$ $R_{gon}=64 \Omega$	$\pm 15$	600	10	$T_j=25^\circ C$ $T_j=125^\circ C$		133 132		ns
Rise time	$t_r$					$T_j=25^\circ C$ $T_j=125^\circ C$		17 23		
Turn-off delay time	$t_{d(off)}$					$T_j=25^\circ C$ $T_j=125^\circ C$		233 291		
Fall time	$t_f$					$T_j=25^\circ C$ $T_j=125^\circ C$		144 159		
Turn-on energy loss per pulse	$E_{on}$					$T_j=25^\circ C$ $T_j=125^\circ C$		0,82 1,13		
Turn-off energy loss per pulse	$E_{off}$					$T_j=25^\circ C$ $T_j=125^\circ C$		0,66 1,01		
Input capacitance	$C_{ies}$							605		pF
Output capacitance	$C_{oss}$	$f=1$ MHz	0	25		$T_j=25^\circ C$		37		
Reverse transfer capacitance	$C_{rss}$							29		
Gate charge	$Q_{Gate}$		$\pm 15$	960	8	$T_j=25^\circ C$		52		nC
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal grease thickness $\leq$ 50um $\lambda = 1$ W/mK						1,99		K/W
<b>Inverter Diode</b>										
Diode forward voltage	$V_F$				10	$T_j=25^\circ C$ $T_j=125^\circ C$	1,25	1,66 1,62	1,95	V
Peak reverse recovery current	$I_{RRM}$					$T_j=25^\circ C$ $T_j=125^\circ C$		11 12		A
Reverse recovery time	$t_{rr}$	$R_{gon}=64 \Omega$	$\pm 15$	600	10	$T_j=25^\circ C$ $T_j=125^\circ C$		329 504		ns
Reverse recovered charge	$Q_{rr}$					$T_j=25^\circ C$ $T_j=125^\circ C$		1,31 2,30	$\mu C$	
Peak rate of fall of recovery current	$di(rec)max/dt$					$T_j=25^\circ C$ $T_j=125^\circ C$		90 39	A/ $\mu s$	
Reverse recovered energy	$E_{rec}$					$T_j=25^\circ C$ $T_j=125^\circ C$		0,49 0,93		mWs
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal grease thickness $\leq$ 50um $\lambda = 1$ W/mK						2,41		K/W

**Characteristic Values**

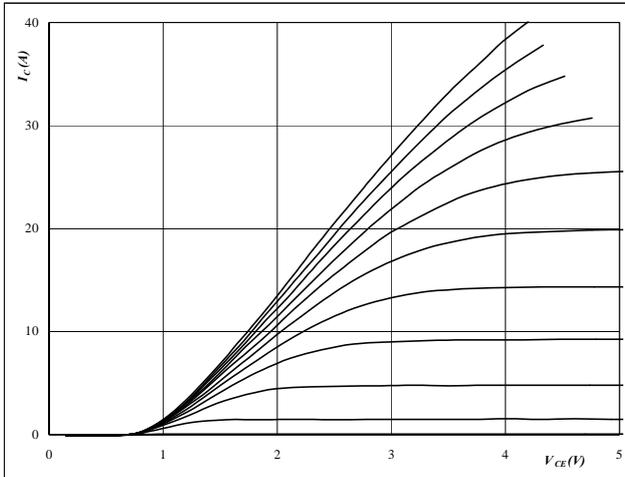
Parameter	Symbol	Conditions					Value			Unit
		$V_{GE}[V]$ or $V_{GS}[V]$	$V_r[V]$ or $V_{CE}[V]$ or $V_{DS}[V]$	$I_c[A]$ or $I_F[A]$ or $I_D[A]$	$T_j$	Min	Typ	Max		
<b>Brake Transistor</b>										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}$			0,0003	$T_j=25^{\circ}C$ $T_j=125^{\circ}C$	5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		8	$T_j=25^{\circ}C$ $T_j=125^{\circ}C$	1,35	1,72 1,96	2,05	V
Collector-emitter cut-off incl diode	$I_{CES}$		0	1200		$T_j=25^{\circ}C$ $T_j=125^{\circ}C$			0,05	mA
Gate-emitter leakage current	$I_{GES}$		20	0		$T_j=25^{\circ}C$ $T_j=125^{\circ}C$			120	nA
Integrated Gate resistor	$R_{gint}$							none		$\Omega$
Turn-on delay time	$t_{d(on)}$	$R_{goff}=64 \Omega$ $R_{gon}=64 \Omega$	$\pm 15$	600	10	$T_j=25^{\circ}C$ $T_j=125^{\circ}C$		131 130		ns
Rise time	$t_r$					$T_j=25^{\circ}C$ $T_j=125^{\circ}C$		15 20		
Turn-off delay time	$t_{d(off)}$					$T_j=25^{\circ}C$ $T_j=125^{\circ}C$		250 312		
Fall time	$t_f$					$T_j=25^{\circ}C$ $T_j=125^{\circ}C$		93 159		
Turn-on energy loss per pulse	$E_{on}$					$T_j=25^{\circ}C$ $T_j=125^{\circ}C$		0,46 0,58		
Turn-off energy loss per pulse	$E_{off}$	$T_j=25^{\circ}C$ $T_j=125^{\circ}C$		0,54 0,82						mWs
Input capacitance	$C_{ies}$							605		pF
Output capacitance	$C_{oss}$	$f=1MHz$	0	25		$T_j=25^{\circ}C$		37		
Reverse transfer capacitance	$C_{rss}$							29		
Gate charge	$Q_{Gate}$		$\pm 15$	960	8	$T_j=25^{\circ}C$		52		nC
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal grease thickness $\leq 50\mu m$ $\lambda = 1 W/mK$						2,09		K/W
<b>Brake Diode</b>										
Diode forward voltage	$V_F$				4	$T_j=25^{\circ}C$ $T_j=125^{\circ}C$	1	1,76 1,87	2,35	V
Reverse leakage current	$I_r$	$R_{gon}=64 \Omega$	$\pm 15$	600	10	$T_j=25^{\circ}C$ $T_j=125^{\circ}C$			250	$\mu A$
Peak reverse recovery current	$I_{RRM}$	$R_{gon}=64 \Omega$ $R_{gon}=64 \Omega$	$\pm 15$	600	10	$T_j=25^{\circ}C$ $T_j=125^{\circ}C$		7 8		A
Reverse recovery time	$t_{rr}$					$T_j=25^{\circ}C$ $T_j=125^{\circ}C$		321 476		ns
Reverse recovered charge	$Q_{rr}$					$T_j=25^{\circ}C$ $T_j=125^{\circ}C$		0,74 0,74		$\mu C$
Peak rate of fall of recovery current	$di(rec)max/dt$					$T_j=25^{\circ}C$ $T_j=125^{\circ}C$		101 59		A/ $\mu s$
Reverse recovery energy	$E_{rec}$					$T_j=25^{\circ}C$ $T_j=125^{\circ}C$		0,30 0,51		mWs
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal grease thickness $\leq 50\mu m$ $\lambda = 1 W/mK$						3,97		K/W
<b>Thermistor</b>										
Rated resistance	R					$T_j=25^{\circ}C$		22000		$\Omega$
Deviation of R100	$\Delta R/R$	R100=1486 $\Omega$				$T_c=100^{\circ}C$	-5		5	%
Power dissipation	P					$T_c=100^{\circ}C$		210		mW
Power dissipation constant						$T_j=25^{\circ}C$		3,5		mW/K
B-value	$B_{(25/50)}$	Tol. $\pm 3\%$				$T_j=25^{\circ}C$				K
B-value	$B_{(25/100)}$	Tol. $\pm 3\%$				$T_j=25^{\circ}C$		4000		K
Vincotech NTC Reference						$T_j=25^{\circ}C$			A	

## Output Inverter

**Figure 1** Output inverter IGBT

**Typical output characteristics**

$$I_C = f(V_{CE})$$

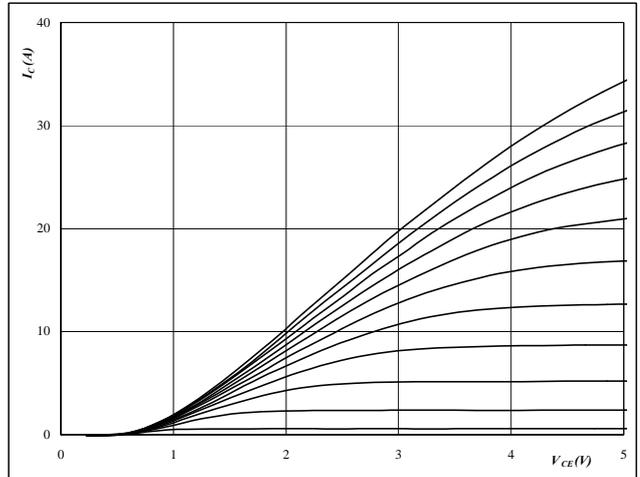


**At**  
 $t_p = 250 \mu s$   
 $T_J = 25 \text{ } ^\circ C$   
 $V_{GE}$  from 7 V to 17 V in steps of 1 V

**Figure 2** Output inverter IGBT

**Typical output characteristics**

$$I_C = f(V_{CE})$$

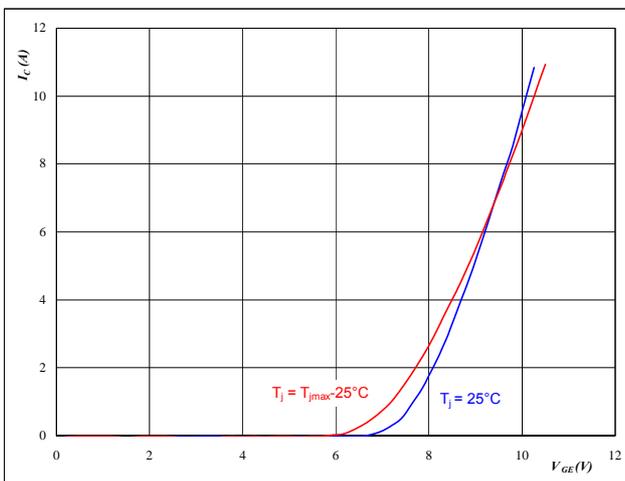


**At**  
 $t_p = 250 \mu s$   
 $T_J = 125 \text{ } ^\circ C$   
 $V_{GE}$  from 7 V to 17 V in steps of 1 V

**Figure 3** Output inverter IGBT

**Typical transfer characteristics**

$$I_C = f(V_{GE})$$

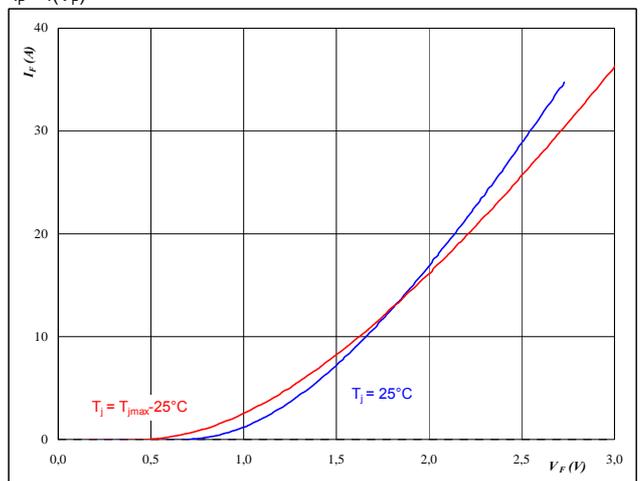


**At**  
 $t_p = 250 \mu s$   
 $V_{CE} = 10 V$

**Figure 4** Output inverter FWD

**Typical diode forward current as a function of forward voltage**

$$I_F = f(V_F)$$



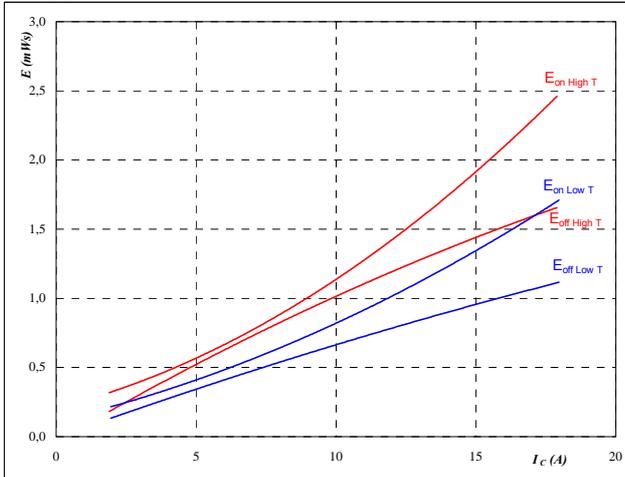
**At**  
 $t_p = 250 \mu s$

## Output Inverter

**Figure 5** Output inverter IGBT

**Typical switching energy losses**  
 as a function of collector current

$$E = f(I_C)$$



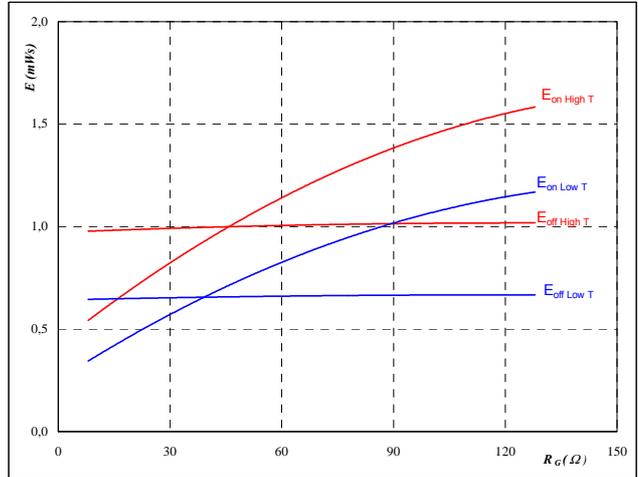
With an inductive load at

$T_J =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω
$R_{goff} =$	64	Ω

**Figure 6** Output inverter IGBT

**Typical switching energy losses**  
 as a function of gate resistor

$$E = f(R_G)$$



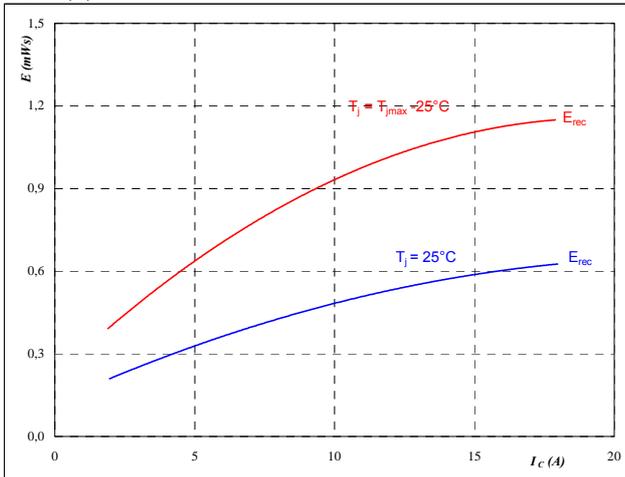
With an inductive load at

$T_J =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	10	A

**Figure 7** Output inverter FWD

**Typical reverse recovery energy loss**  
 as a function of collector current

$$E_{rec} = f(I_C)$$



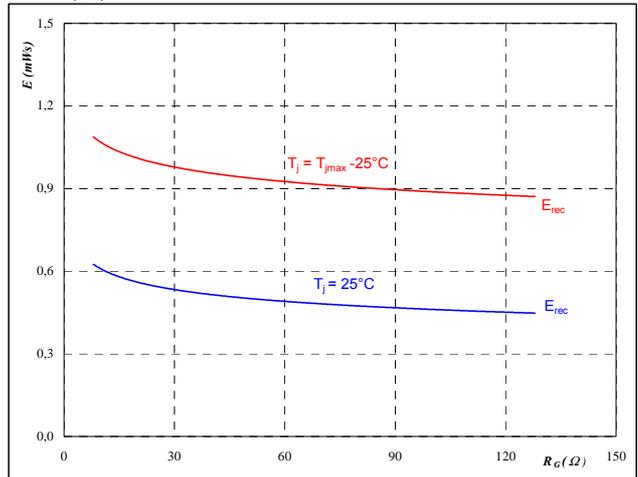
With an inductive load at

$T_J =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω

**Figure 8** Output inverter FWD

**Typical reverse recovery energy loss**  
 as a function of gate resistor

$$E_{rec} = f(R_G)$$



With an inductive load at

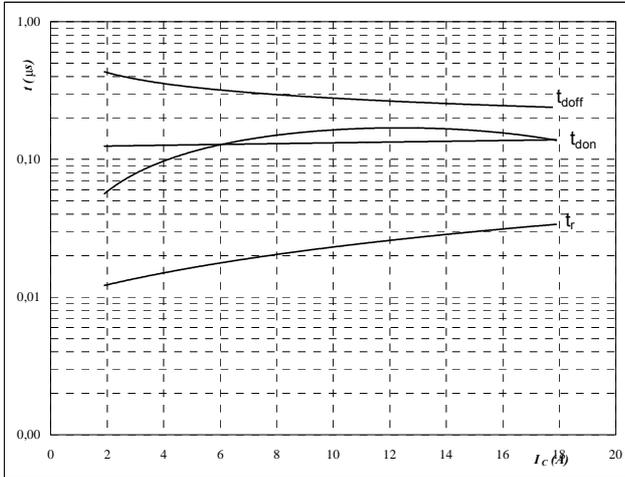
$T_J =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	10	A

## Output Inverter

**Figure 9** Output inverter IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



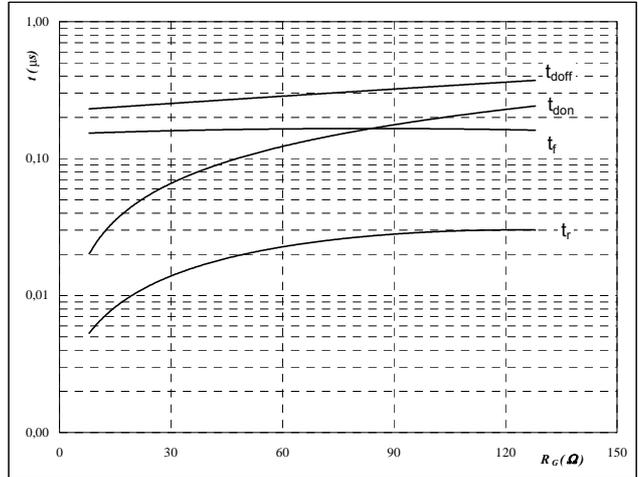
With an inductive load at

$T_J =$	125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω
$R_{goff} =$	64	Ω

**Figure 10** Output inverter IGBT

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



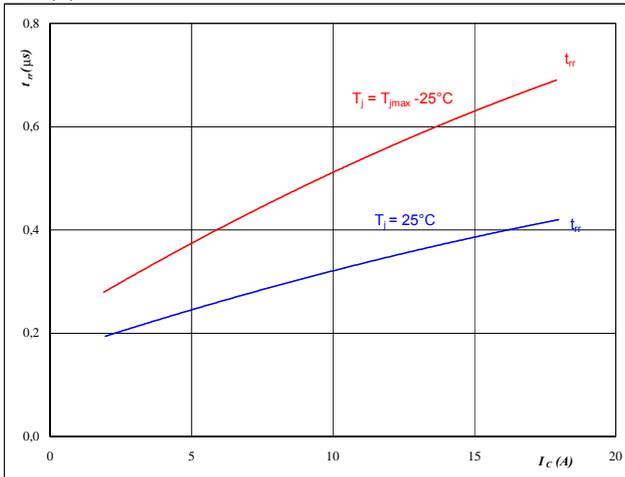
With an inductive load at

$T_J =$	125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	10	A

**Figure 11** Output inverter FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_C)$$



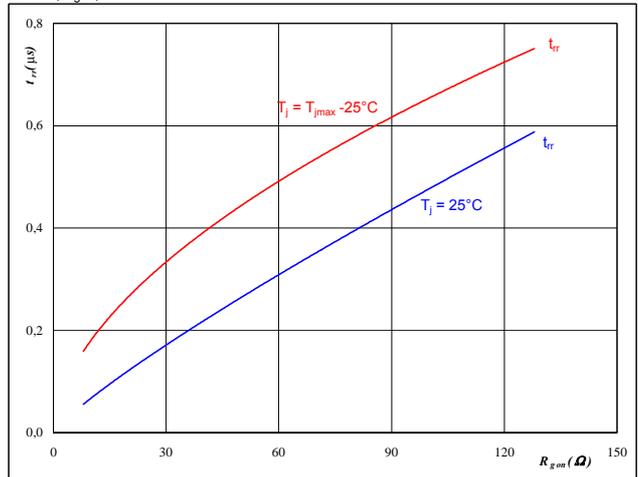
At

$T_J =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω

**Figure 12** Output inverter FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At

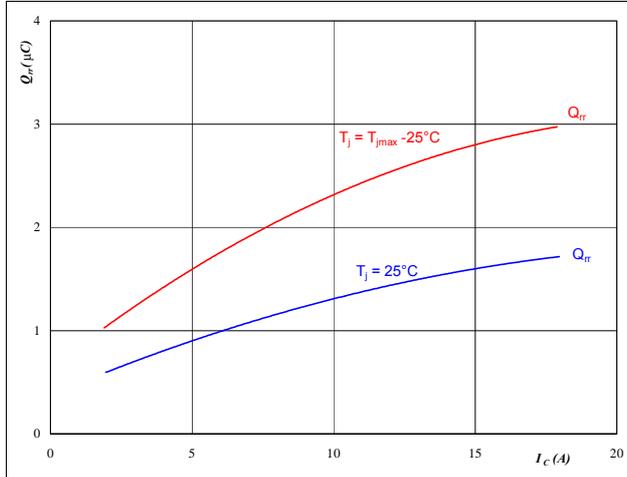
$T_J =$	25/125	°C
$V_R =$	600	V
$I_F =$	10	A
$V_{GE} =$	±15	V

## Output Inverter

**Figure 13** Output inverter FWD

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_C)$$



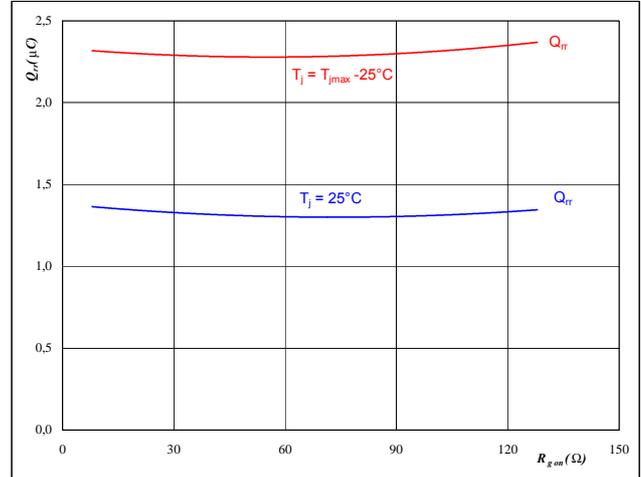
**At**

$T_j =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω

**Figure 14** Output inverter FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$



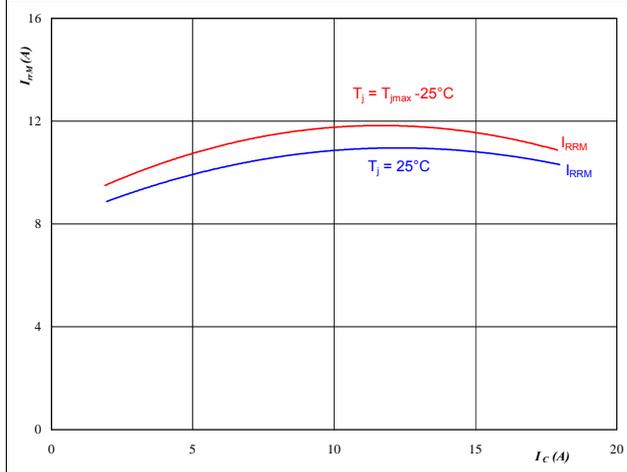
**At**

$T_j =$	25/125	°C
$V_R =$	600	V
$I_F =$	10	A
$V_{GE} =$	±15	V

**Figure 15** Output inverter FWD

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_C)$$



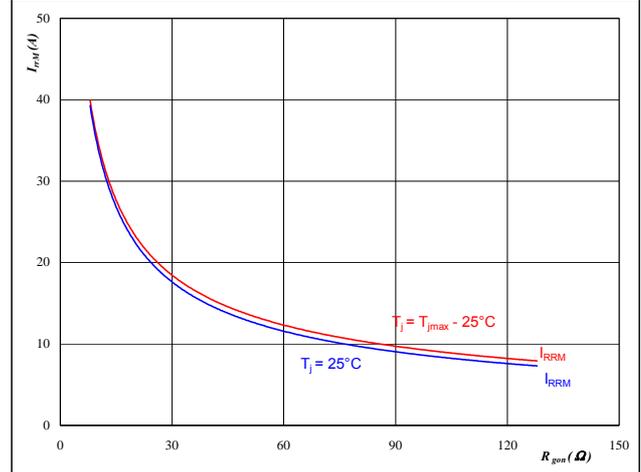
**At**

$T_j =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω

**Figure 16** Output inverter FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$



**At**

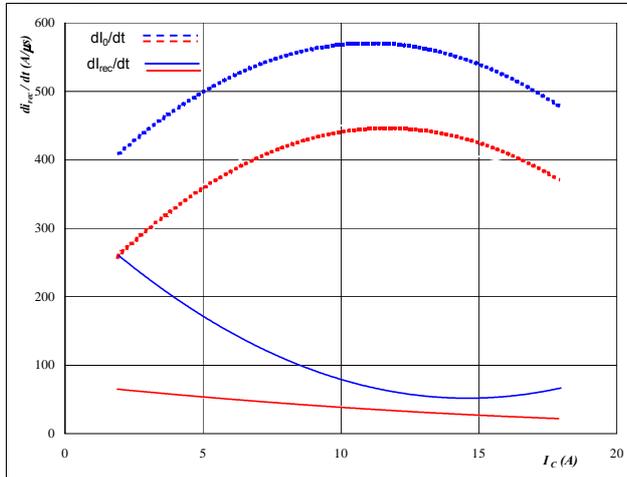
$T_j =$	25/125	°C
$V_R =$	600	V
$I_F =$	10	A
$V_{GE} =$	±15	V

## Output Inverter

Figure 17 Output inverter FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$$di_o/dt, di_{rec}/dt = f(I_c)$$

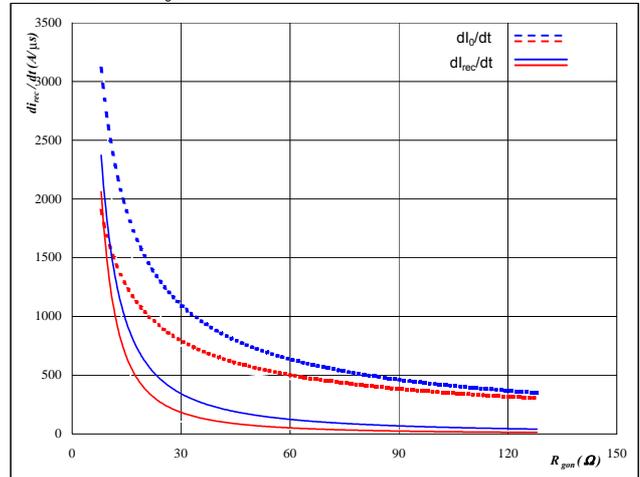


At  
 $T_j = 25/125$  °C  
 $V_{CE} = 600$  V  
 $V_{GE} = \pm 15$  V  
 $R_{gon} = 64$  Ω

Figure 18 Output inverter FWD

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$$di_o/dt, di_{rec}/dt = f(R_{gon})$$

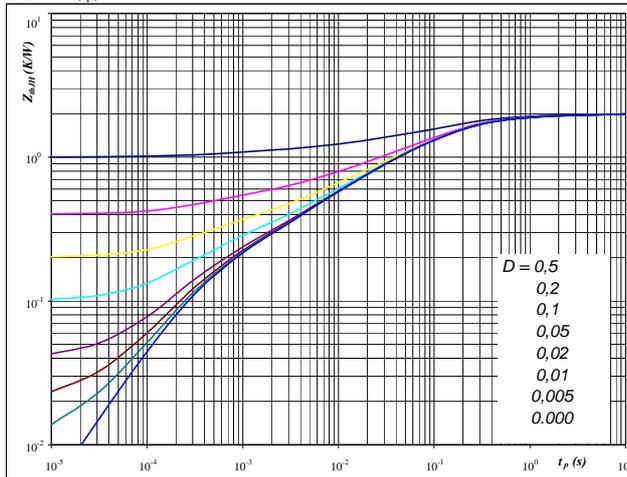


At  
 $T_j = 25/125$  °C  
 $V_R = 600$  V  
 $I_F = 10$  A  
 $V_{GE} = \pm 15$  V

Figure 19 Output inverter IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$



At  
 $D = t_p / T$   
 $R_{thJH} = 1,99$  K/W     $R_{thJH} = 1,93$  K/W

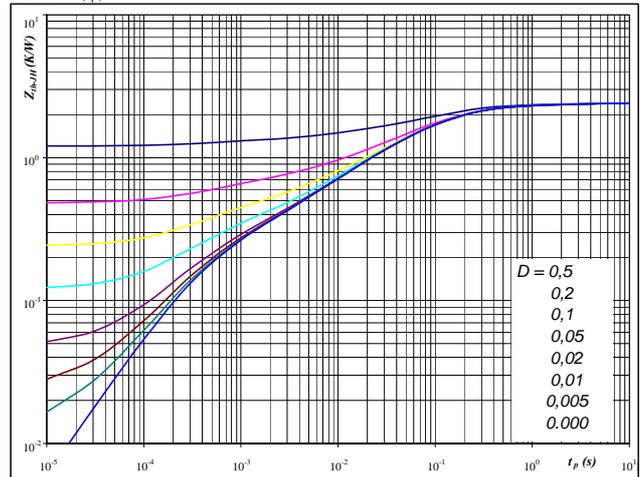
### IGBT thermal model values

Thermal grease		Phase change interface	
R (C/W)	Tau (s)	R (C/W)	Tau (s)
0,09	4,8E+00	0,09	4,7E+00
0,35	4,4E-01	0,34	4,2E-01
0,86	1,0E-01	0,83	9,7E-02
0,39	1,6E-02	0,37	1,5E-02
0,17	2,9E-03	0,16	2,8E-03
0,14	3,5E-04	0,14	3,4E-04

Figure 20 Output inverter FWD

FWD transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$



At  
 $D = t_p / T$   
 $R_{thJH} = 2,41$  K/W     $R_{thJH} = 2,33$  K/W

### FWD thermal model values

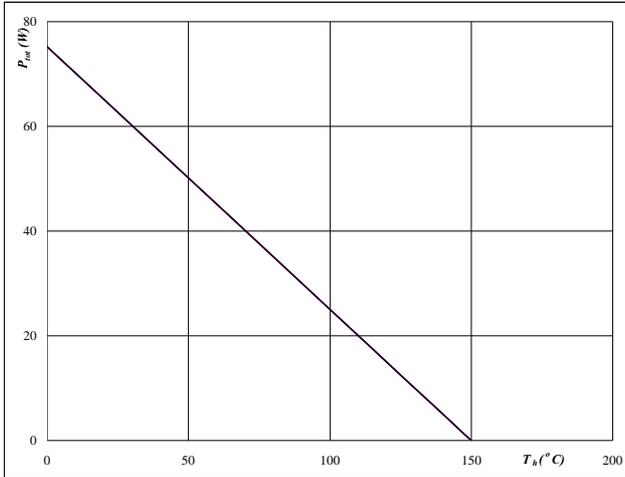
Thermal grease		Phase change interface	
R (C/W)	Tau (s)	R (C/W)	Tau (s)
0,12	2,9E+00	0,12	2,8E+00
0,37	3,4E-01	0,36	3,3E-01
1,06	8,3E-02	1,03	8,0E-02
0,48	1,8E-02	0,47	1,7E-02
0,21	2,8E-03	0,20	2,7E-03
0,17	3,5E-04	0,17	3,4E-04

## Output Inverter

**Figure 21** Output inverter IGBT

**Power dissipation as a function of heatsink temperature**

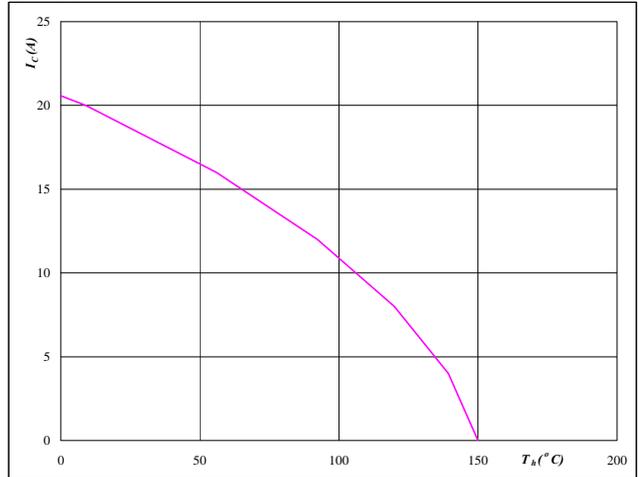
$$P_{tot} = f(T_h)$$


**At**  
 $T_j = 175$  °C

**Figure 22** Output inverter IGBT

**Collector current as a function of heatsink temperature**

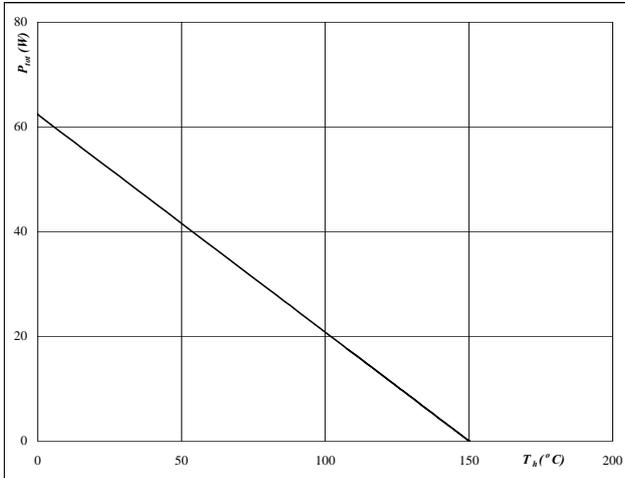
$$I_C = f(T_h)$$


**At**  
 $T_j = 175$  °C  
 $V_{GE} = 15$  V

**Figure 23** Output inverter FWD

**Power dissipation as a function of heatsink temperature**

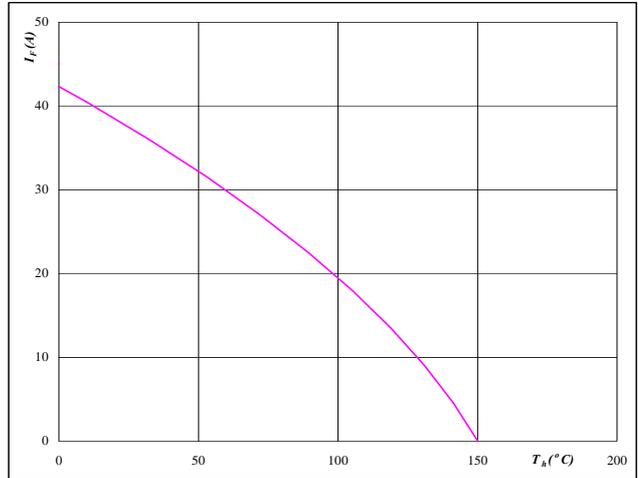
$$P_{tot} = f(T_h)$$


**At**  
 $T_j = 175$  °C

**Figure 24** Output inverter FWD

**Forward current as a function of heatsink temperature**

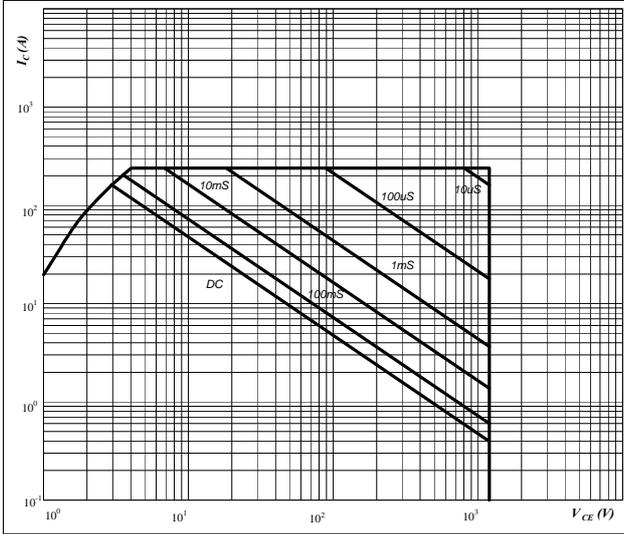
$$I_F = f(T_h)$$


**At**  
 $T_j = 175$  °C

## Output Inverter

**Figure 25** Output inverter IGBT

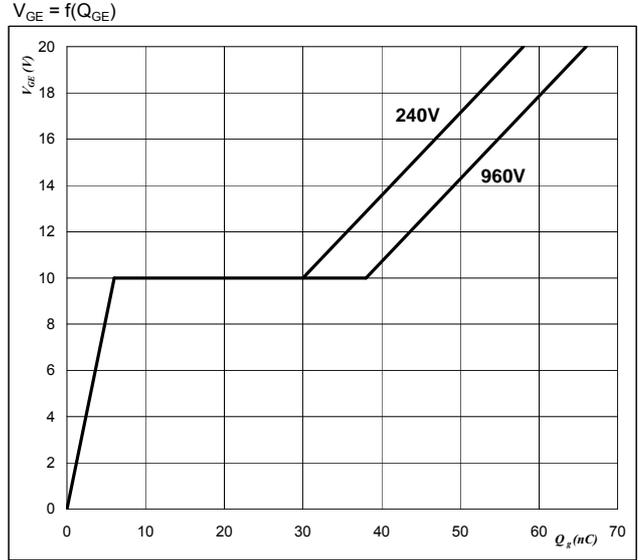
Safe operating area as a function of collector-emitter voltage  
 $I_C = f(V_{CE})$



**At**  
 D = single pulse  
 $T_n = 80$  °C  
 $V_{GE} = \pm 15$  V  
 $T_j = T_{jmax}$  °C

**Figure 26** Output inverter IGBT

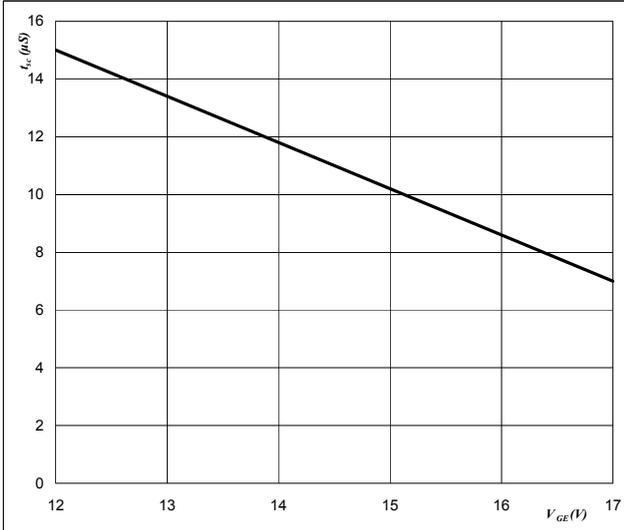
Gate voltage vs Gate charge



**At**  
 $I_C = 10$  A

**Figure 27** Output inverter IGBT

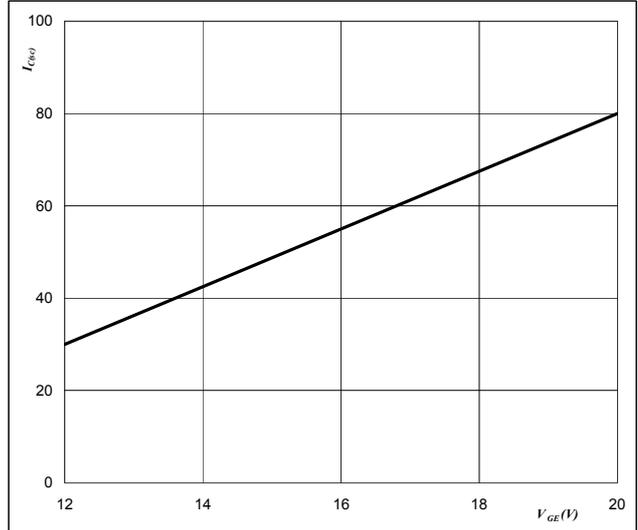
Short circuit withstand time as a function of gate-emitter voltage  
 $t_{sc} = f(V_{GE})$



**At**  
 $V_{CE} = 1200$  V  
 $T_j \leq 175$  °C

**Figure 28** Output inverter IGBT

Typical short circuit collector current as a function of gate-emitter voltage  
 $V_{GE} = f(Q_{GE})$

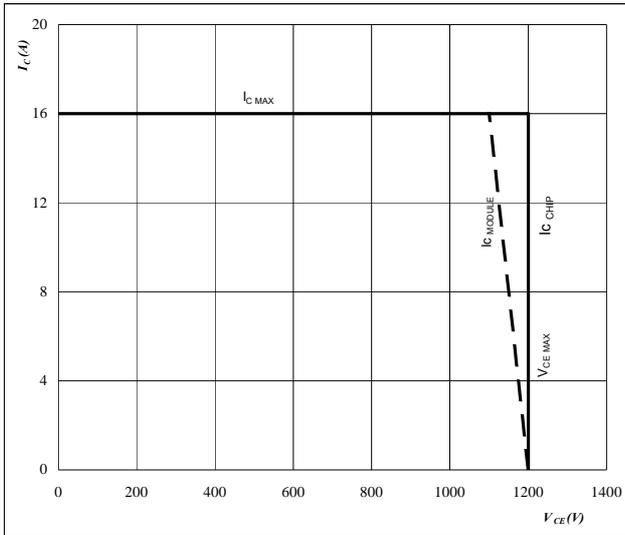


**At**  
 $V_{CE} \leq 1200$  V  
 $T_j = 175$  °C

**Figure 29** IGBT

**Reverse bias safe operating area**

$$I_C = f(V_{CE})$$


**At**

$$T_J = T_{J\text{max}} - 25 \text{ } ^\circ\text{C}$$

$$U_{\text{ocminus}} = U_{\text{ccplus}}$$

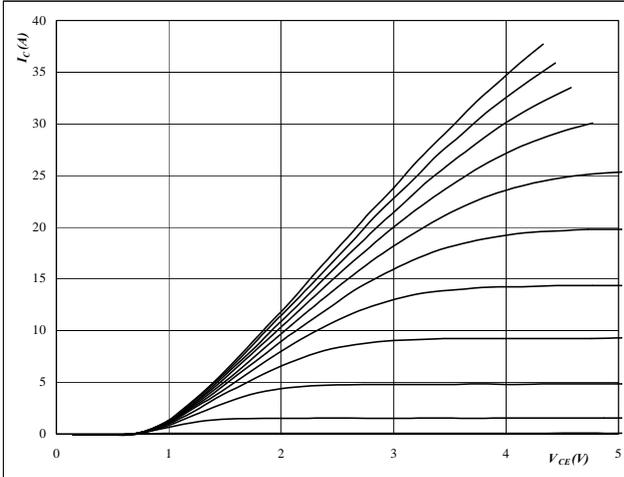
Switching mode : 3 level switching

## Brake

**Figure 1** Brake IGBT

**Typical output characteristics**

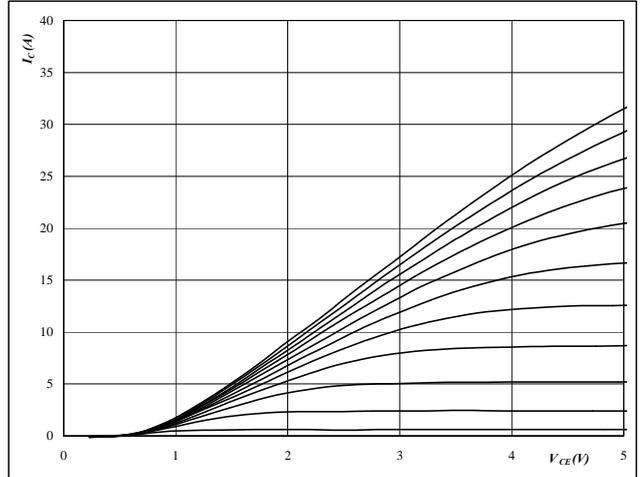
$I_C = f(V_{CE})$


**At**
 $t_p = 250 \mu s$   
 $T_J = 25 \text{ }^\circ C$   
 $V_{GE}$  from 7 V to 17 V in steps of 1 V

**Figure 2** Brake IGBT

**Typical output characteristics**

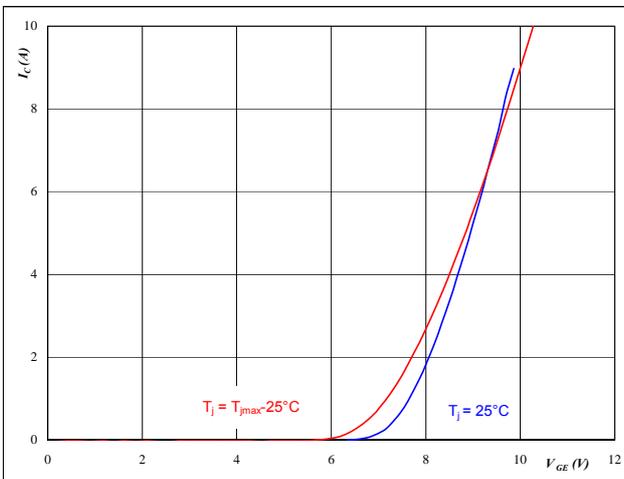
$I_C = f(V_{CE})$


**At**
 $t_p = 250 \mu s$   
 $T_J = 125 \text{ }^\circ C$   
 $V_{GE}$  from 7 V to 17 V in steps of 1 V

**Figure 3** Brake IGBT

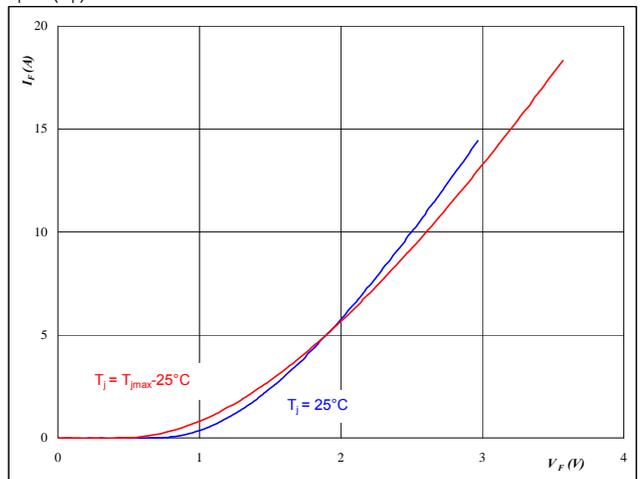
**Typical transfer characteristics**

$I_C = f(V_{GE})$


**At**
 $t_p = 250 \mu s$   
 $V_{CE} = 10 \text{ V}$ 
**Figure 4** Brake FWD

**Typical diode forward current as a function of forward voltage**

$I_F = f(V_F)$

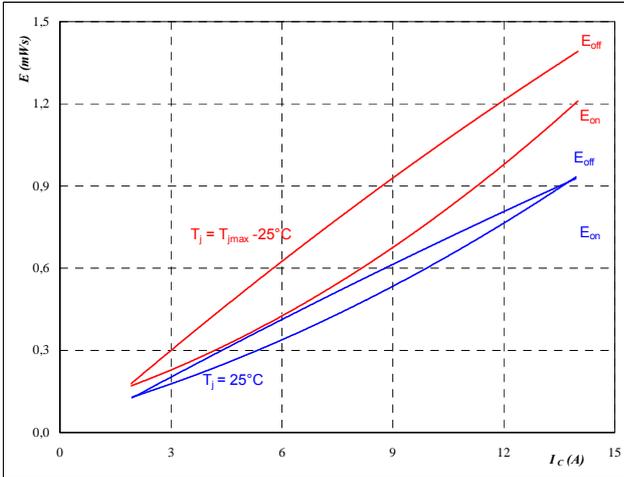

**At**
 $t_p = 250 \mu s$

## Brake

**Figure 5** Brake IGBT

**Typical switching energy losses**  
 as a function of collector current

$$E = f(I_C)$$



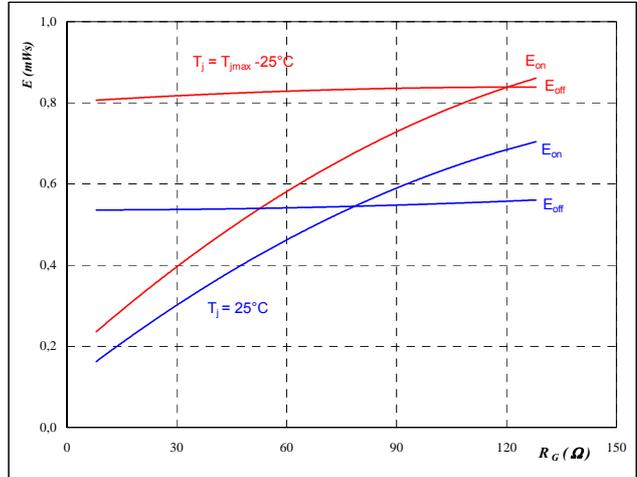
With an inductive load at

$T_J =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω
$R_{goff} =$	64	Ω

**Figure 6** Brake IGBT

**Typical switching energy losses**  
 as a function of gate resistor

$$E = f(R_G)$$



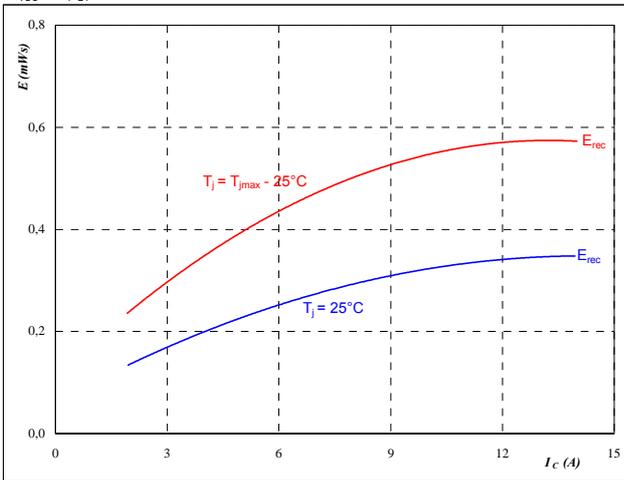
With an inductive load at

$T_J =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	8	A

**Figure 7** Brake FWD

**Typical reverse recovery energy loss**  
 as a function of collector current

$$E_{rec} = f(I_C)$$



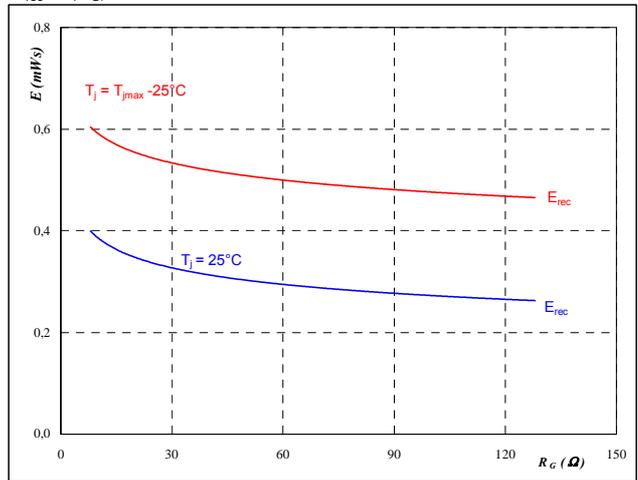
With an inductive load at

$T_J =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω

**Figure 8** Brake FWD

**Typical reverse recovery energy loss**  
 as a function of gate resistor

$$E_{rec} = f(R_G)$$



With an inductive load at

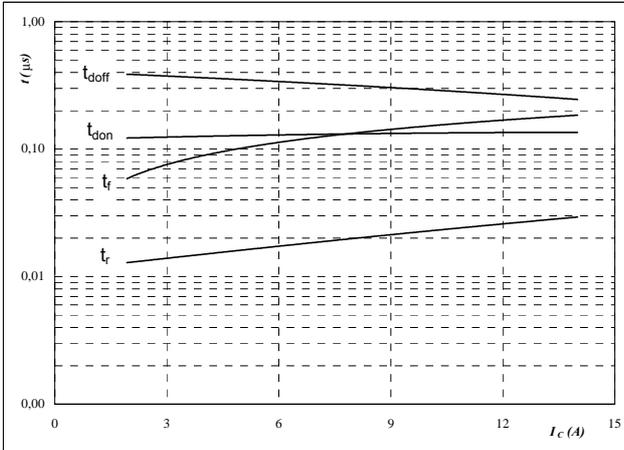
$T_J =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	8	A

## Brake

**Figure 9** Brake IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



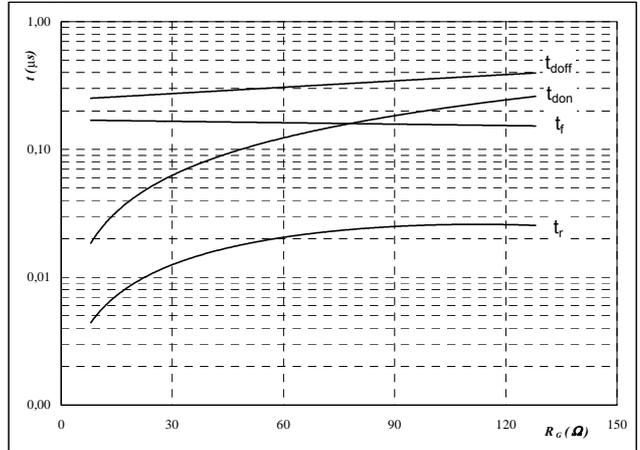
With an inductive load at

$T_J =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω
$R_{goff} =$	64	Ω

**Figure 10** Brake IGBT

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



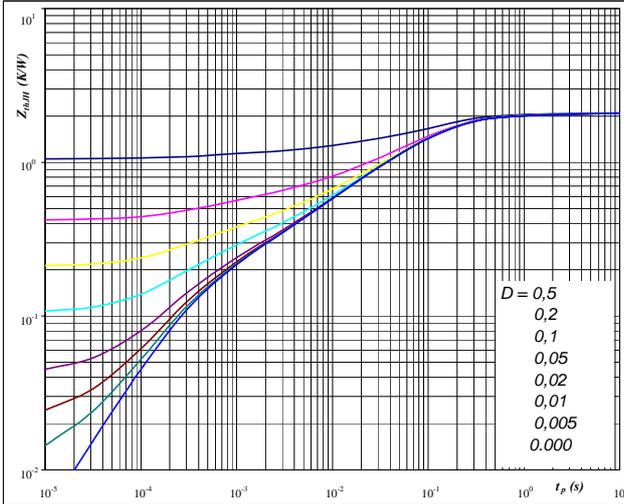
With an inductive load at

$T_J =$	25/125	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	8	A

**Figure 11** Brake IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$

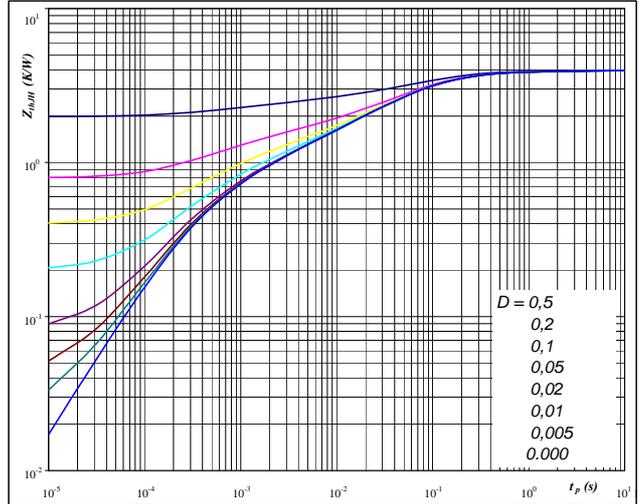


<b>At</b>	$D =$	$t_p / T$	
Thermal grease		Phase change interface	
$R_{thJH} =$	2,09	K/W	$R_{thJH} =$ 0,60 K/W

**Figure 12** Brake FWD

FWD transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$



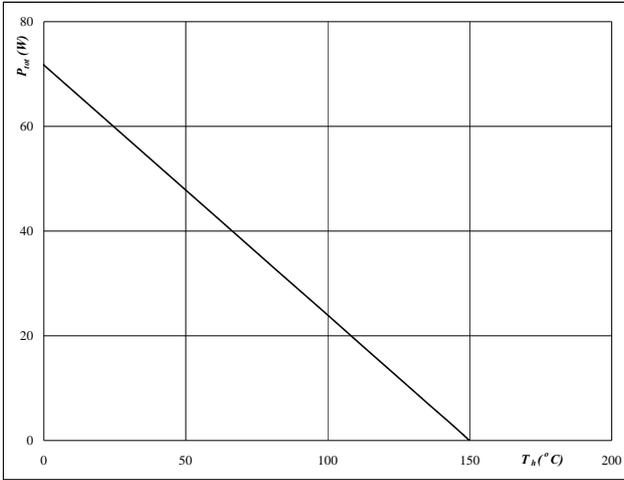
<b>At</b>	$D =$	$t_p / T$	
Thermal grease		Phase change interface	
$R_{thJH} =$	3,97	K/W	$R_{thJH} =$ 1,27 K/W

## Brake

**Figure 13** Brake IGBT

**Power dissipation as a function of heatsink temperature**

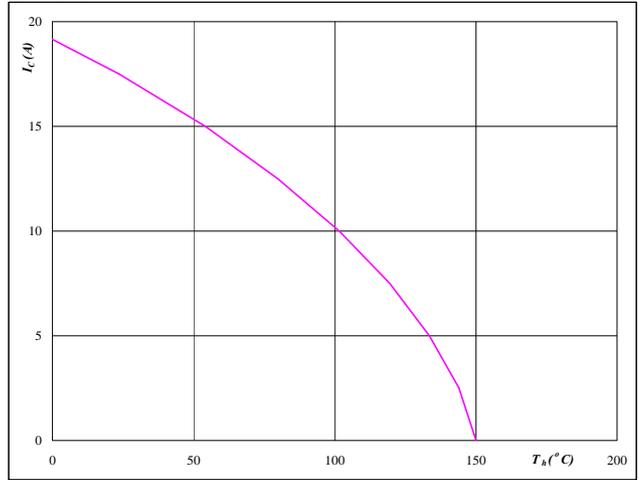
$$P_{tot} = f(T_h)$$


**At**  
 $T_j = 175$  °C

**Figure 14** Brake IGBT

**Collector current as a function of heatsink temperature**

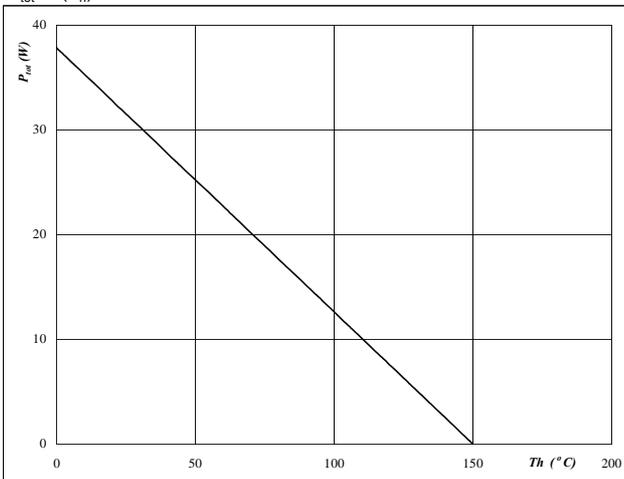
$$I_C = f(T_h)$$


**At**  
 $T_j = 175$  °C  
 $V_{GE} = 15$  V

**Figure 15** Brake FWD

**Power dissipation as a function of heatsink temperature**

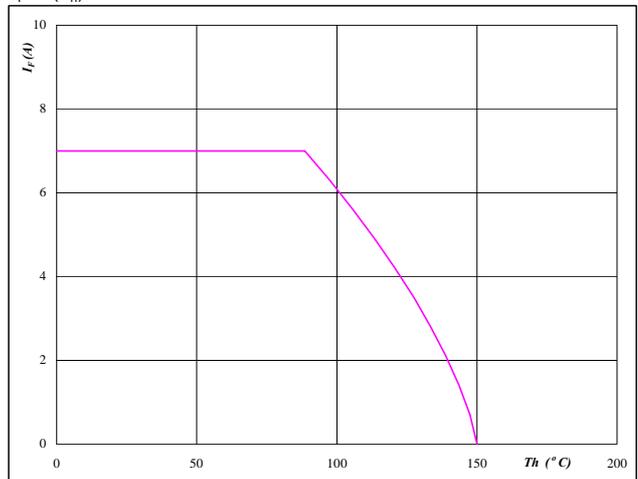
$$P_{tot} = f(T_h)$$


**At**  
 $T_j = 175$  °C

**Figure 16** Brake FWD

**Forward current as a function of heatsink temperature**

$$I_F = f(T_h)$$

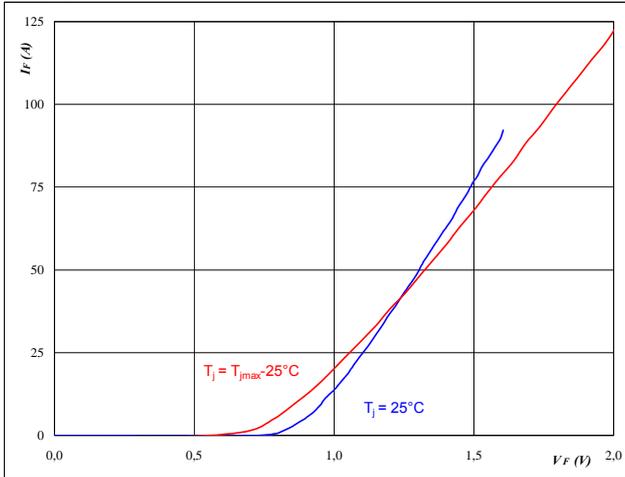

**At**  
 $T_j = 175$  °C

## Input Rectifier Bridge

**Figure 1** Rectifier diode

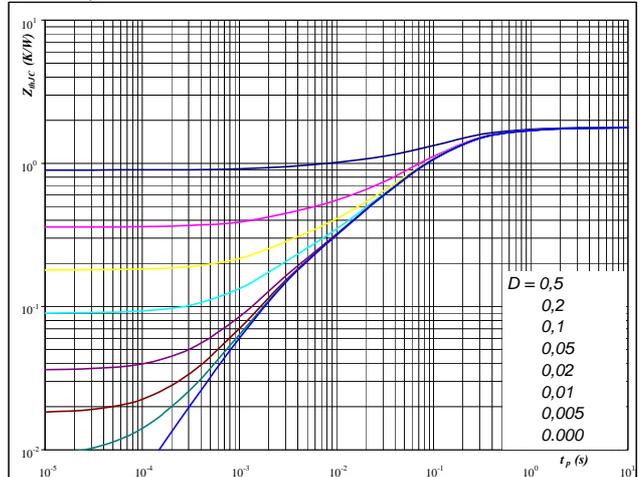
**Typical diode forward current as a function of forward voltage**

$$I_F = f(V_F)$$


**At**  
 $t_p = 250 \mu s$ 
**Figure 2** Rectifier diode

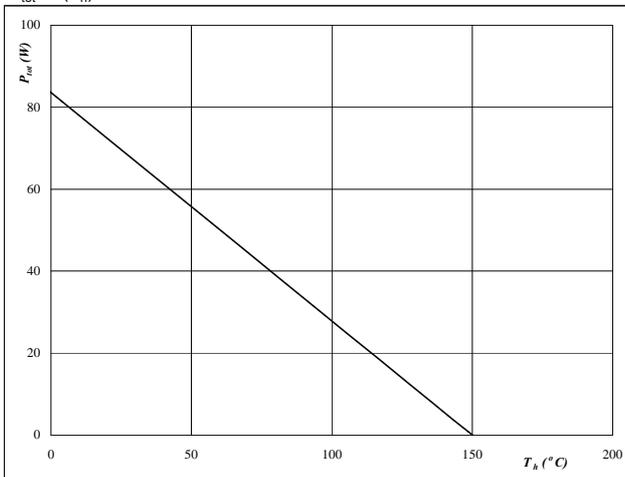
**Diode transient thermal impedance as a function of pulse width**

$$Z_{thJH} = f(t_p)$$


**At**  
 $D = t_p / T$   
 $R_{thJH} = 1,795 \text{ K/W}$ 
**Figure 3** Rectifier diode

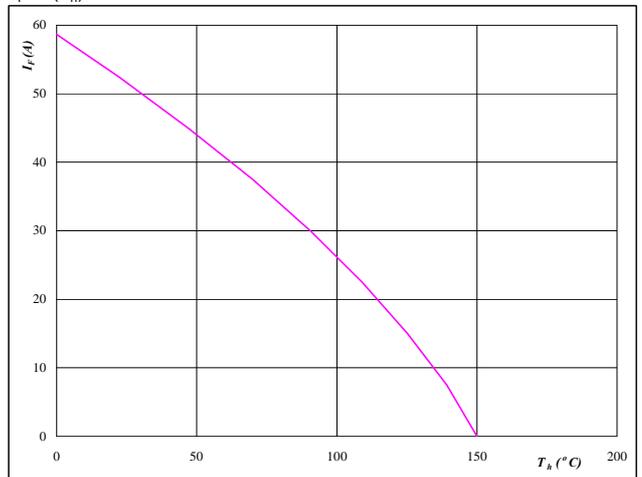
**Power dissipation as a function of heatsink temperature**

$$P_{tot} = f(T_h)$$


**At**  
 $T_j = 150 \text{ °C}$ 
**Figure 4** Rectifier diode

**Forward current as a function of heatsink temperature**

$$I_F = f(T_h)$$

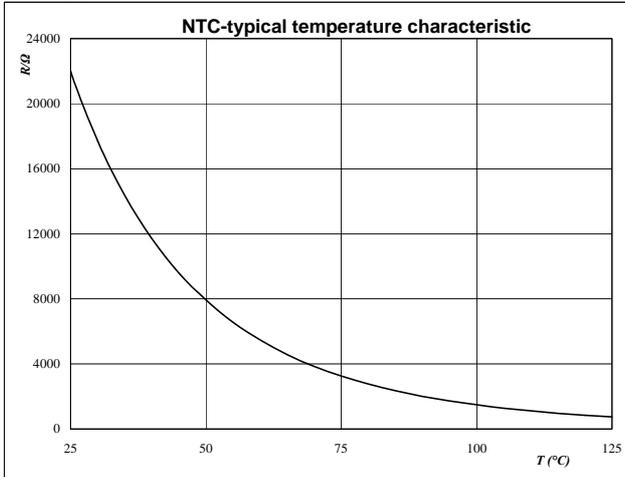

**At**  
 $T_j = 150 \text{ °C}$

## Thermistor

**Figure 1** Thermistor

Typical NTC characteristic  
 as a function of temperature

$$R_T = f(T)$$


**Figure 2** Thermistor

Typical NTC resistance values

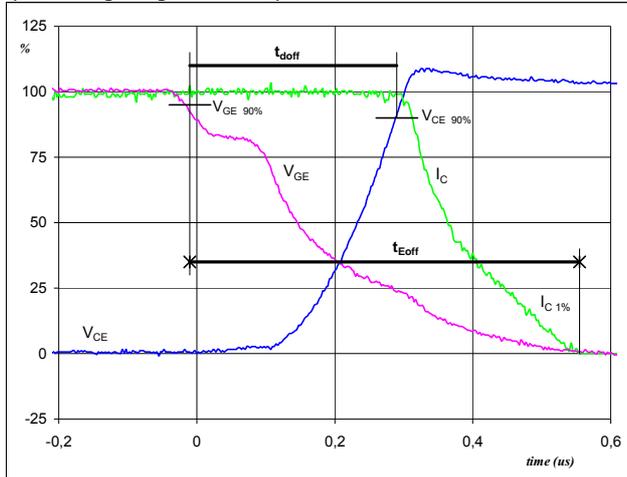
$$R(T) = R_{25} \cdot e^{\left( B_{25/100} \left( \frac{1}{T} - \frac{1}{T_{25}} \right) \right)} \quad [\Omega]$$

T [°C]	R <sub>nom</sub> [Ω]	R <sub>min</sub> [Ω]	R <sub>max</sub> [Ω]	ΔR/R [±%]
-55	2089434,5	1506495,4	2672373,6	27,9
0	71804,2	59724,4	83884	16,8
10	43780,4	37094,4	50466,5	15,3
20	27484,6	23684,6	31284,7	13,8
25	22000	19109,3	24890,7	13,1
30	17723,3	15512,2	19934,4	12,5
60	5467,9	4980,6	5955,1	8,9
70	3848,6	3546	4151,1	7,9
80	2757,7	2568,2	2947,1	6,9
90	2008,9	1889,7	2128,2	5,9
<b>100</b>	<b>1486,1</b>	<b>1411,8</b>	<b>1560,4</b>	<b>5</b>
150	400,2	364,8	435,7	8,8

## Switching Definitions Output Inverter

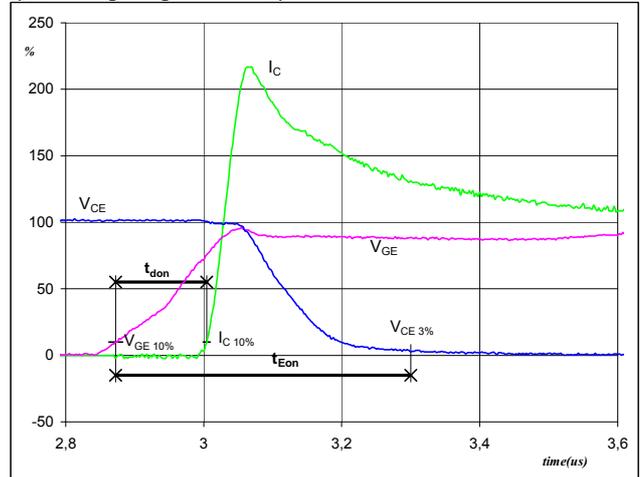
General conditions	
$T_j$	= 125 °C
$R_{gon}$	= 64 $\Omega$
$R_{goff}$	= 64 $\Omega$

**Figure 1** Output inverter IGBT

**Turn-off Switching Waveforms & definition of  $t_{doff}$ ,  $t_{Eoff}$**   
 ( $t_{Eoff}$  = integrating time for  $E_{off}$ )


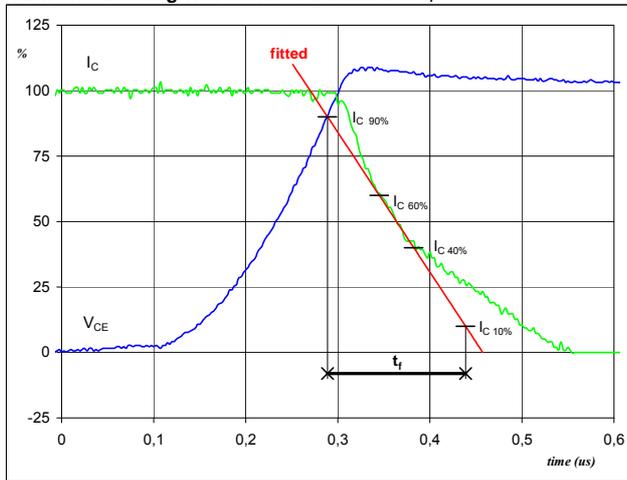
$V_{GE}(0\%)$	=	-15	V
$V_{GE}(100\%)$	=	15	V
$V_C(100\%)$	=	600	V
$I_C(100\%)$	=	10	A
$t_{doff}$	=	0,29	$\mu s$
$t_{Eoff}$	=	0,56	$\mu s$

**Figure 2** Output inverter IGBT

**Turn-on Switching Waveforms & definition of  $t_{don}$ ,  $t_{Eon}$**   
 ( $t_{Eon}$  = integrating time for  $E_{on}$ )


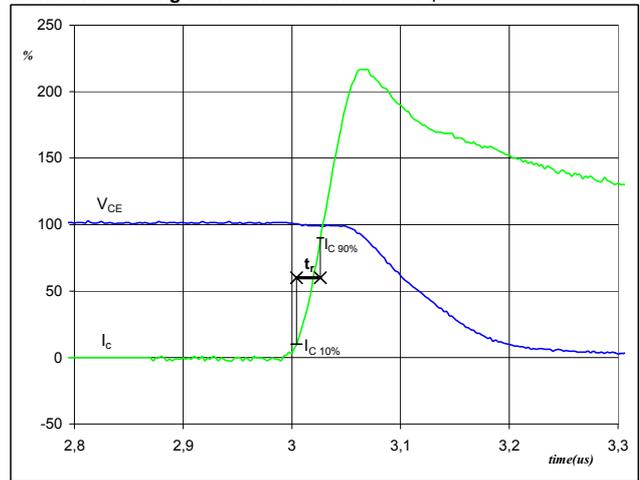
$V_{GE}(0\%)$	=	-15	V
$V_{GE}(100\%)$	=	15	V
$V_C(100\%)$	=	600	V
$I_C(100\%)$	=	10	A
$t_{don}$	=	0,13	$\mu s$
$t_{Eon}$	=	0,43	$\mu s$

**Figure 3** Output inverter IGBT

**Turn-off Switching Waveforms & definition of  $t_f$** 


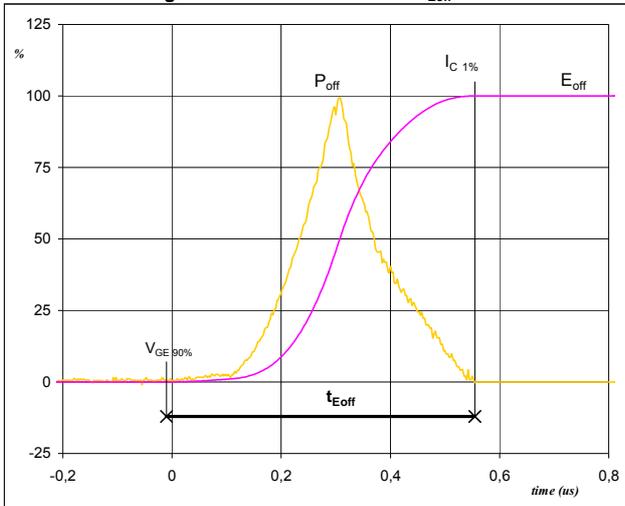
$V_C(100\%)$	=	600	V
$I_C(100\%)$	=	10	A
$t_f$	=	0,16	$\mu s$

**Figure 4** Output inverter IGBT

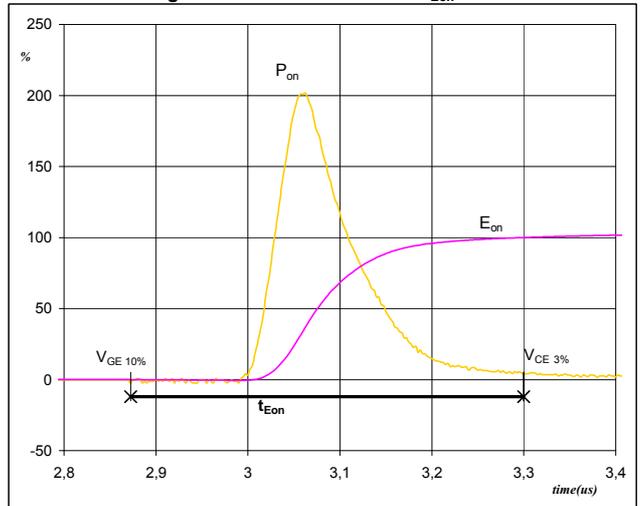
**Turn-on Switching Waveforms & definition of  $t_r$** 


$V_C(100\%)$	=	600	V
$I_C(100\%)$	=	10	A
$t_r$	=	0,02	$\mu s$

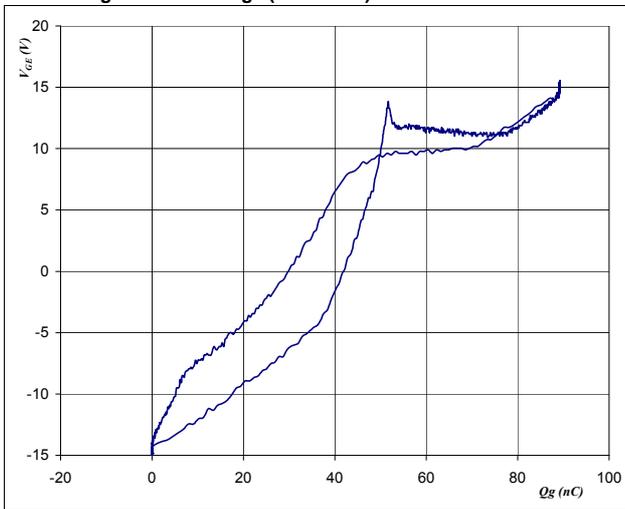
## Switching Definitions Output Inverter

**Figure 5** Output inverter IGBT  
**Turn-off Switching Waveforms & definition of  $t_{Eoff}$** 


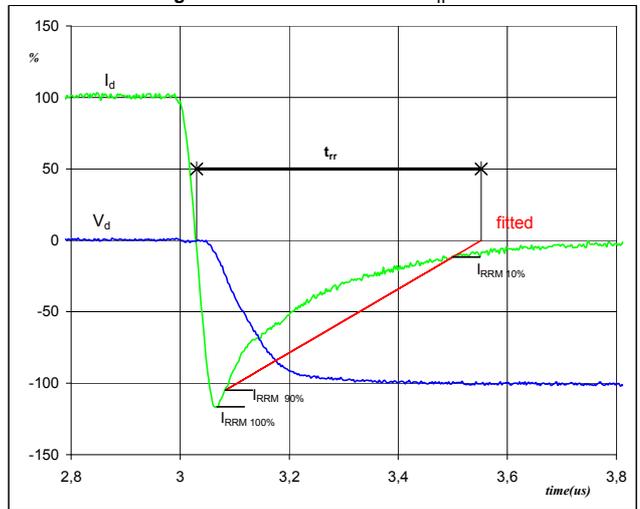
$P_{off}(100\%) = 5,97$  kW  
 $E_{off}(100\%) = 1,01$  mJ  
 $t_{Eoff} = 0,56$   $\mu$ s

**Figure 6** Output inverter IGBT  
**Turn-on Switching Waveforms & definition of  $t_{Eon}$** 


$P_{on}(100\%) = 5,97$  kW  
 $E_{on}(100\%) = 1,13$  mJ  
 $t_{Eon} = 0,43$   $\mu$ s

**Figure 7** Output inverter FWD  
**Gate voltage vs Gate charge (measured)**


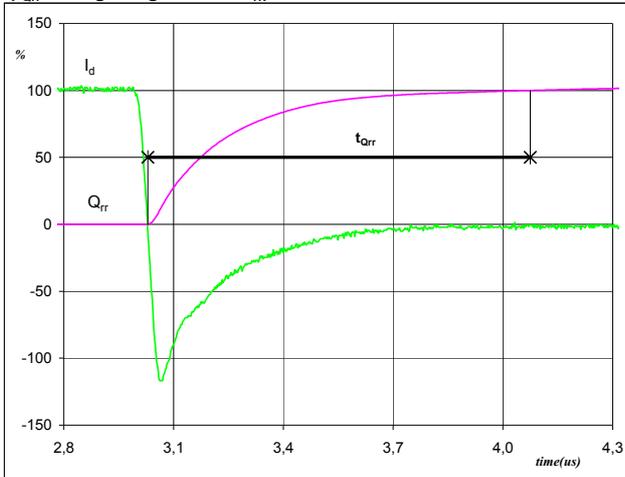
$V_{GEoff} = -15$  V  
 $V_{GEon} = 15$  V  
 $V_C(100\%) = 600$  V  
 $I_C(100\%) = 10$  A  
 $Q_g = 89,25$  nC

**Figure 8** Output inverter IGBT  
**Turn-off Switching Waveforms & definition of  $t_{rr}$** 


$V_d(100\%) = 600$  V  
 $I_d(100\%) = 10$  A  
 $I_{RRM}(100\%) = 12$  A  
 $t_{rr} = 0,50$   $\mu$ s

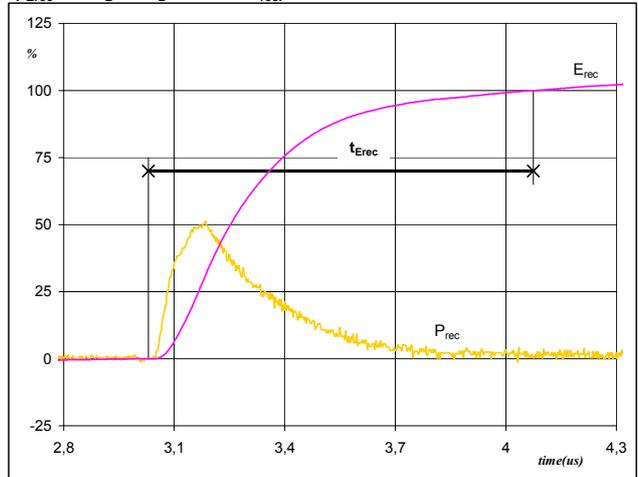
## Switching Definitions Output Inverter

**Figure 9** Output inverter FWD

**Turn-on Switching Waveforms & definition of  $t_{Qrr}$**   
 ( $t_{Qrr}$  = integrating time for  $Q_{rr}$ )


$I_d$ (100%) =	10	A
$Q_{rr}$ (100%) =	2,30	$\mu\text{C}$
$t_{Qrr}$ =	1,04	$\mu\text{s}$

**Figure 10** Output inverter FWD

**Turn-on Switching Waveforms & definition of  $t_{Erec}$**   
 ( $t_{Erec}$  = integrating time for  $E_{rec}$ )


$P_{rec}$ (100%) =	5,97	kW
$E_{rec}$ (100%) =	0,93	mJ
$t_{Erec}$ =	1,04	$\mu\text{s}$

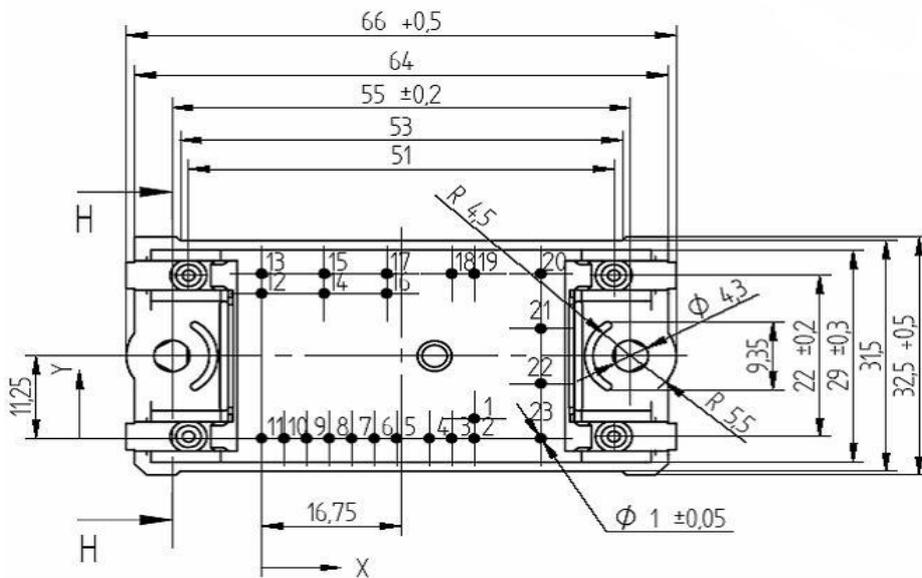
### Ordering Code and Marking - Outline - Pinout

#### Ordering Code & Marking

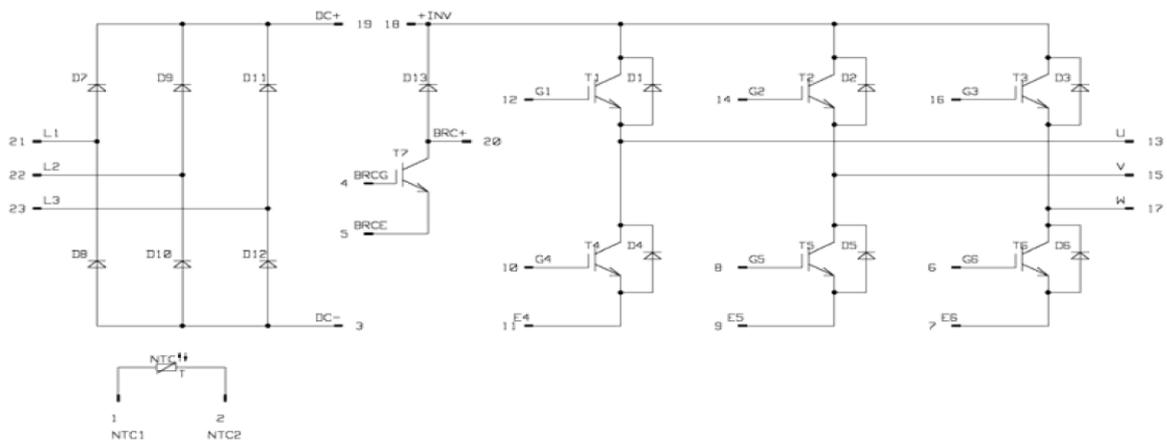
Version	Ordering Code	in DataMatrix as	in packaging barcode as
without thermal paste 12mm housing	V23990-P549-A01-PM	P549-A01	P549-A01

#### Outline

Pin Table		
Pin	X	Y
1	25,5	2,7
2	25,5	0
3	22,8	0
4	20,1	0
5	16,2	0
6	13,5	0
7	10,8	0
8	8,1	0
9	5,4	0
10	2,7	0
11	0	0
12	0	19,8
13	0	22,5
14	7,5	19,8
15	7,5	22,5
16	15	19,8
17	15	22,5
18	22,8	22,5
19	25,5	22,5
20	33,5	22,5
21	33,5	15
22	33,5	7,5
23	33,5	0



#### Pinout



This drawing contains the maximum configuration. Depending upon types, some components may be left. See in part list.

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Datasheet Status	Product Status	Definition
Target	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice. The data contained is exclusively intended for technically trained staff.
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